

To the Honorable Commissioner of Patents and Trademarks: Please



thereof.

; party(ies):

1. Name of conveying party(ies):

Peter Jeffrey Brofman Scott Ira Langenthal
Shaji Farooq Sudipta Kumar Ray
John U. Knickerbocker Kathleen Ann Stalter

101082105

Name: International Business Machines Corporation

Internal Address: N/A

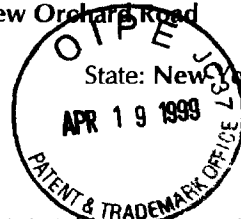
Additional name(s) of conveying party(ies) attached?
[] Yes [X] No

Street Address: New Orchard Road

City: Armonk

State: New York

Zip Code: 10504



Additional Name(s) & Address(es) attached?

[] Yes [X] No

3. Nature of Conveyance:

[X] Assignment [] Merger
[] Security Agreement [] Change of Name
[] Other

Execution Date: 11/20/98, 11/13/98, 11/17/98,
11/18/98, 11/16/98, 11/18/98.

4. Application number(s) or patent number(s):

4-19-99

Title of Application: PROCESS FOR FORMING CONE SHAPED SOLDER FOR CHIP INTERCONNECTION

If this document is being filed together with a new application, the execution date of the
application is: 11/20/98, 11/13/98, 11/17/98, 11/18/98, 11/16/98, 11/18/98

A. Patent Application No.(s) B. Patent No.(s)

S/N 09/233,383

Additional numbers attached? [] Yes [X] No

5. Name and address of party whom correspond-
ence concerning document should be mailed:

Name: DeLIO & PETERSON, LLC
Street Address: 121 Whitney Avenue
City: New Haven State: CT
Zip Code: 06510-1241

6. Total number of applications and patents
involved:.....[1]

7. Total Fee (37 CFR 3.41) \$40.00
[] Enclosed
[X] Authorized to be charged to Deposit
Account number below
[X] Any deficiencies in the enclosed fees

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS
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TRADEMARKS, WASHINGTON, D.C. 20231, ON

April 16, 1999

RobinAnn Zeno

Signature Date 4/16/99

8. Assignee IBM Corporation Deposit Account
Number:

09-0458 (FI- 180)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any
attached copy is a true copy of the original document.

Ira D. Blecker
Name of Person Signing
Registration No. 29,894

Signature

Date 4/16/99

Phone No.: 914-894- 2580

Total number of pages including cover sheet, attachments, and document: [3]

ASSIGNMENT

Whereas, we

Inventor and
City

(1) **Peter Jeffrey Brofman**
County of **Dutchess**

City of **Hopewell Junction**
and State of **New York 12533**

and

(2) **Shaji Farooq**
County of **Dutchess**

City of **Hopewell Junction**
and State of **New York 12533**

and

(3) **John U. Knickerbocker**
County of **Dutchess**

City of **Hopewell Junction**
and State of **New York 12533**

and

(4) **Scott Ira Langenthal**
County of **Dutchess**

City of **Hyde Park**
and State of **New York 12538-3124**

and

5) **Sudipta Kumar Ray**
County of **Dutchess**

City of **Wappingers Falls**
and State of **New York 12590**

and

(6) **Kathleen Ann Stalter**
County of **Dutchess**

City of **Hopewell Junction**
and State of **New York 12533**

Title

have invented certain improvements in
**PROCESS FOR FORMING CONE SHAPED SOLDER
FOR CHIP INTERCONNECTION**

Date That
Inventors
Signed the
Declaration

and have executed, respectively, a United States patent application therefor on
(1) 11/20, 1997, and (2) November 13, 1998, and
(3) 11/17, 1998, and (4) 11/18, 1998, and
(5) 11/16, 1996, and (6) 11/15, 1998

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

ASSIGNMENT (continued)

TITLE: PROCESS FOR FORMING CONE SHAPED SOLDER FOR CHIP INTERCONNECTION

City (1) Signed at East Fishkill, New York
 City State
 Date on Nov 20, 1998 Peter Jeffrey Brofman signature
Peter Jeffrey Brofman

City (2) Signed at East Fishkill, New York
 City State
 Date on 11/13, 1998 Shaji Farooq signature
Shaji Farooq

City (3) Signed at East Fishkill, New York
 City State
 Date on 11/17, 1998 John U. Knickerbocker signature
John U. Knickerbocker

City (4) Signed at East Fishkill, New York
 City State
 Date on 11/18, 1998 Scott Ira Langenthal signature
Scott Ira Langenthal

City (5) Signed at East Fishkill, New York
 City State
 Date on 11/18, 1998 Sudipta Kumar Ray signature
Sudipta Kumar Ray

City (6) Signed at East Fishkill, New York
 City State
 Date on 11/18, 1998 Kathleen Ann Stalter signature
Kathleen Ann Stalter

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